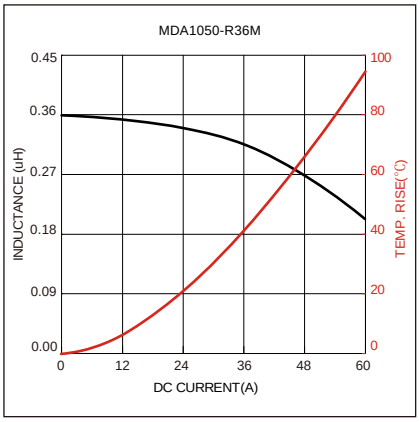
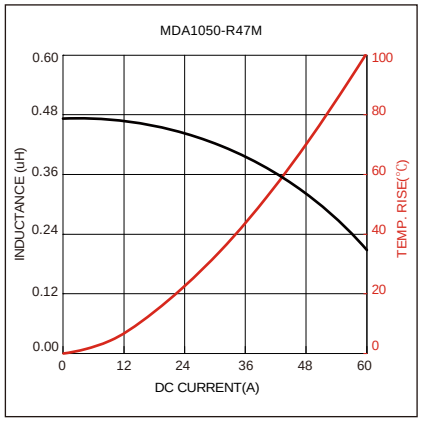
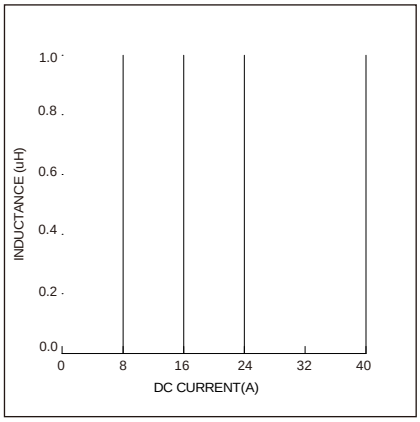
MDA Series
SMD Low Profile High Current Molded Inductor
Size 1050

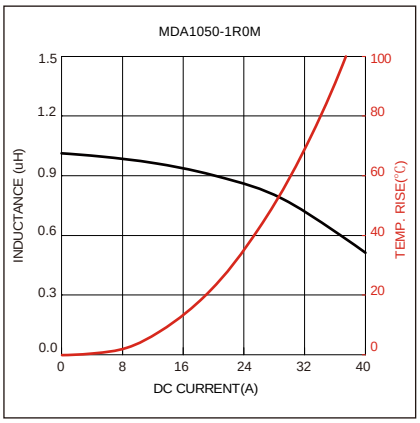
Part No	Inductance @ 100KHz/1V	Tolerance	Temperature Rise Current Typ. (A)	Current Typ. (A)	DC Resistance Typ.	DC Resistance Max.	E

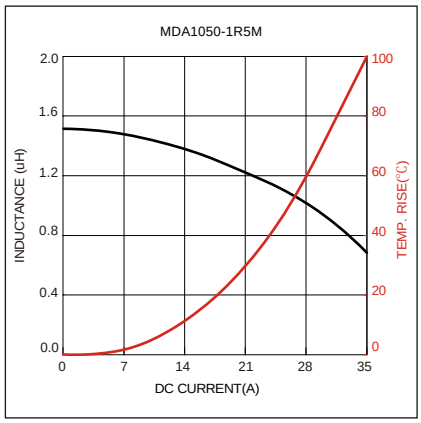
Typical Electrical Characteristics:

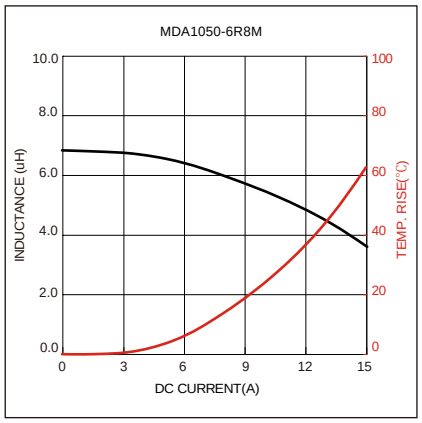


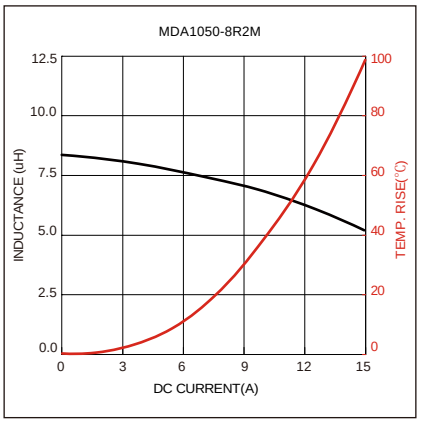


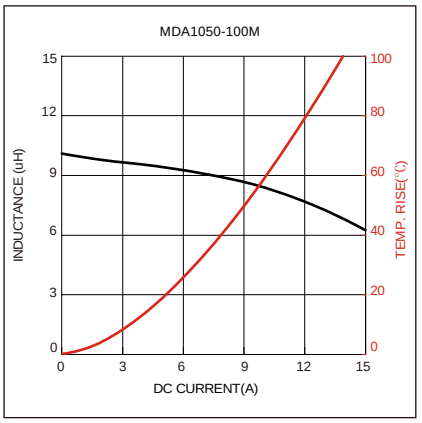


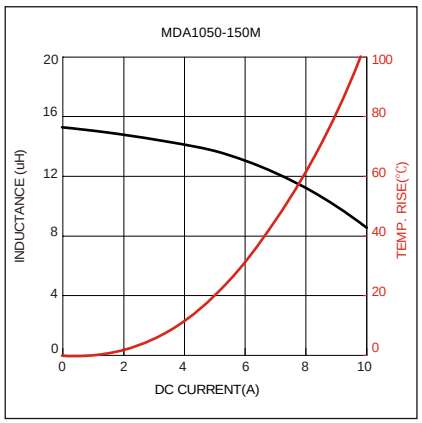


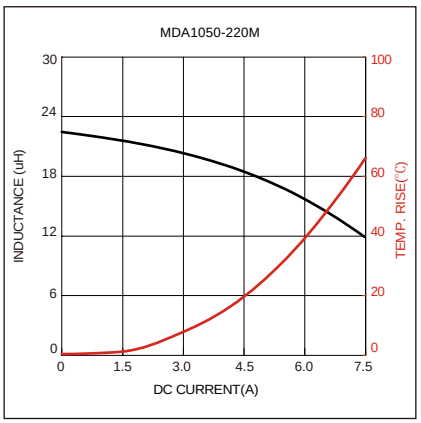


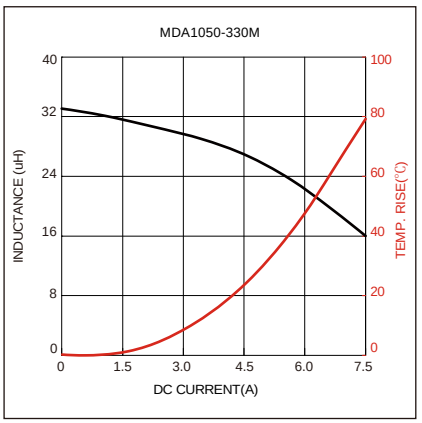

MDA1050-6R8M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
10.0
8.0
6.0
4.0
2.0
0.0
100
80
60
40
20
0
0
3
6
9
12
15

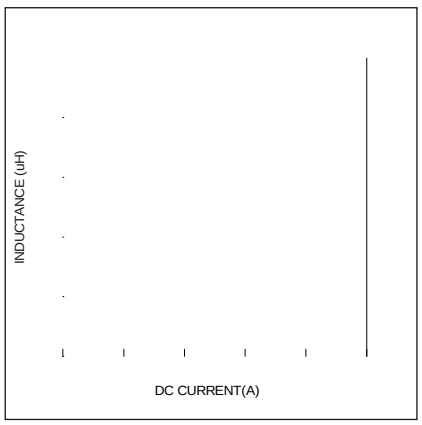

MDA1050-8R2M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
12.5
10.0
7.5
5.0
2.5
0.0
100
80
60
40
20
0
0
3
6
9
12
15


MDA1050-100M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
15
12
9
6
3
0
100
80
60
40
20
0
0
3
6
9
12
15

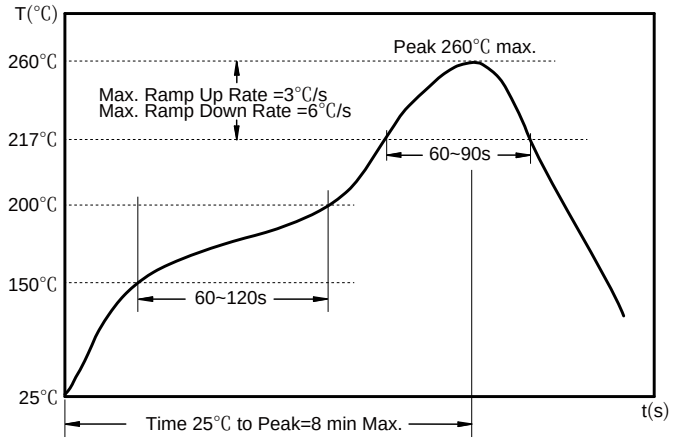

MDA1050-150M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
20
16
12
8
4
0
100
80
60
40
20
0
0
2
4
6
8
10


MDA1050-220M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
30
24
18
12
6
0
100
80
60
40
20
0
0
1.5
3.0
4.5
6.0
7.5


MDA1050-330M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
40
32
24
16
8
0
100
80
60
40
20
0
0
1.5
3.0
4.5
6.0
7.5


INDUCTANCE (uH)
DC CURRENT(A)

Soldering Reflow:



Preheat condition: 150 ~200℃/ 60~120 sec.

Allowed time above 217℃: 60~90 sec.

Max temperature: 260℃.

Max time at max temperature: 10 sec.

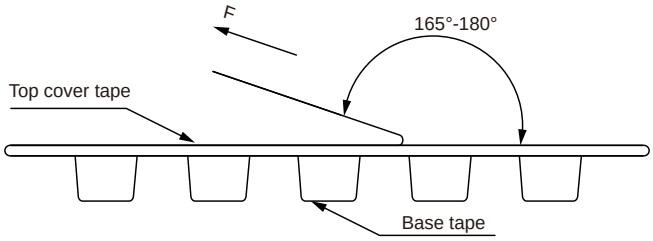
Allowed Reflow time: 2x max.

Packaging Information:

Tape Dimension：

Series	A0 (mm)	B0 (mm)
MDA1050	10.4 ± 0.1	

Peel force of top cover tape:

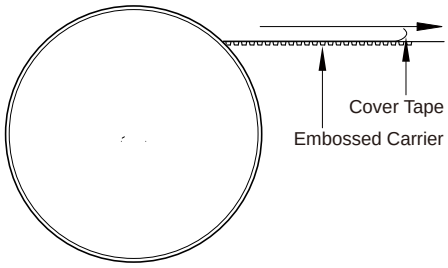


The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	KH+Printing Inductance+period)

Reel Dimension：[mm]



Packaging Quantity: